

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







R46 Series, Class X2, 275 VAC, 125°C



Overview

The R46 Series is constructed of metallized polypropylene film encapsulated with self-extinguishing resin in a box of material meeting the requirements of UL 94 V-0.

Applications

For worldwide use in electromagnetic interference (EMI) suppression in across-the-line applications requiring X2 safety classification. Intended for use in situations where capacitor failure would not result in exposure to electric shock. Not for use in "series with mains" type applications.

Benefits

Approvals: ENEC, UL, cUL, CQC

Class X2 (IEC 60384-14)

Rated voltage: 275 VAC 50/60 Hz
Capacitance range: 0.01 – 1 µF
Lead spacing: 10.0 – 22.5 mm

Capacitance tolerance: ±20%, ±10%

Climatic category: 40/125/56, IEC 60068-1

• Tape and reel in accordance with IEC 60286-2

· RoHS Compliant and lead-free terminations

• Operating temperature range of -40°C to +125°C

100% screening factory test at 2,200 VDC/1,500 VAC

· Self-healing properties



Part Number System

R46	K	N	3220	00	H1	M
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Packaging	Internal Use	Capacitance Tolerance
X2, Metallized Polypropylene	K = 275	F = 10.0 I = 15.0 N = 22.5	The last three digits represent significant figures. The first digit specifies number of zeros to be added.	See Ordering Options Table	H = High Temperature H1 H2 H3 H4	K = ±10% M = ±20%

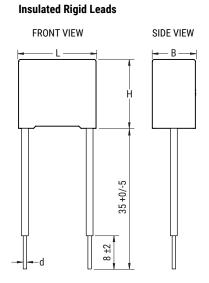


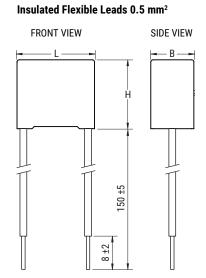
Ordering Options Table

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	Lead and Packaging Code
	Standard Lead and Packaging Options		
	Bulk (Bag) – Short Leads	4+2/-0	00
	Ammo Pack	H ₀ = 18.5+/-0.5	DQ
	Other Lead and Packaging Options		
	Tape & Reel (Large Reel)	H ₀ = 18.5+/-0.5	CK
	Bulk (Bag) – Short Leads	2.7+0.5/-0	JA
10,	Bulk (Bag) – Short Leads	3.5+0.5/-0	JB
15,	Bulk (Bag) – Short Leads	4.0+0.5/-0	JE
22.5	Bulk (Bag) – Short Leads	3.2+0.3/-0.2	JH
	Bulk (Bag) – Long Leads	18+1/-1	JM
	Bulk (Bag) – Long Leads	30+5/-0	40
	Bulk (Bag) – Long Leads	25+2/-1	50
	Bulk (Bag) – Insulated Rigid Leads	30+5/-0 (sp 8+2/-2)	51
	Bulk (Bag) – Insulated Flexible Leads	150+5/-5 (sp 8+2/-2)	52



Dimensions - Millimeters





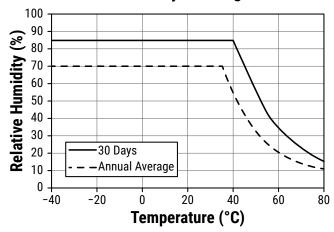
	p B H L		L		d				
Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
10.0	+/-0.4	5.0	+0.2	11.0	+0.1	13.0	+0.2	0.6	+/-0.05
10.0	+/-0.4	6.0	+0.2	12.0	+0.1	13.0	+0.2	0.6	+/-0.05
15.0	+/-0.4	5.0	+0.2	11.0	+0.1	18.0	+0.3	0.6	+/-0.05
15.0	+/-0.4	6.0	+0.2	12.0	+0.1	18.0	+0.3	0.6	+/-0.05
15.0	+/-0.4	6.0	+0.2	17.5	+0.1	18.0	+0.3	0.6	+/-0.05
15.0	+/-0.4	7.5	+0.2	13.5	+0.1	18.0	+0.5	0.6	+/-0.05
15.0	+/-0.4	7.5	+0.2	18.5	+0.1	18.0	+0.5	0.8	+/-0.05
15.0	+/-0.4	8.5	+0.2	14.5	+0.1	18.0	+0.5	0.6	+/-0.05
15.0	+/-0.4	9.0	+0.2	12.5	+0.1	18.0	+0.5	0.6	+/-0.05
15.0	+/-0.4	10.0	+0.2	16.0	+0.1	18.0	+0.5	0.8	+/-0.05
15.0	+/-0.4	11.0	+0.2	19.0	+0.1	18.0	+0.5	0.8	+/-0.05
15.0	+/-0.4	13.0	+0.2	12.0	+0.1	18.0	+0.5	0.8	+/-0.05
22.5	+/-0.4	6.0	+0.2	15.0	+0.1	26.5	+0.3	0.8	+/-0.05
22.5	+/-0.4	7.0	+0.2	16.0	+0.1	26.5	+0.3	0.8	+/-0.05
22.5	+/-0.4	10.0	+0.2	18.5	+0.1	26.5	+0.3	0.8	+/-0.05
22.5	+/-0.4	11.0	+0.2	20.0	+0.1	26.5	+0.3	0.8	+/-0.05
22.5	+/-0.4	13.0	+0.2	22.0	+0.1	26.5	+0.3	0.8	+/-0.05
		Note: Se	e Ordering O	ptions Table	e for lead len	gth (LL/H0)	options.		



Performance Characteristics

Polypropylene film				
Metal layer deposited by evaporation under vacuum				
Non-inductive type				
Tinned wire				
Plastic case, thermosetting resin filled. Box material is solvent resistant and flame retardant according to UL94.				
IEC 60384-14, EN 60384-14				
275 VAC (50/60 Hz), 560 VDC				
0.010 μF to 1 μF				
E6 series (IEC 60063) measured at 1 kHz and +20±1°C				
±10%, ±20%				
-40°C to +125°C				
40/125/56 IEC 60068-1				
Storage time: ≤ 24 months from the date marked on the label package				
Average relative humidity per year ≤ 70%				
RH ≤ 85% for 30 days randomly distributed throughout the year				
Dew is absent				
Temperature: -40 to 80°C (see "Maximum Humidity in Storage Conditions" graph below)				
ENEC, UL, cUL, CQC				

Maximum Humidity in Storage Conditions



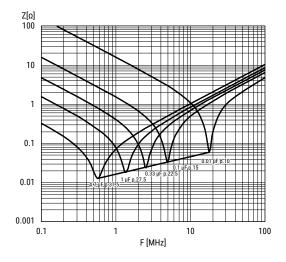


Performance Characteristics cont'd

Dissipation Factor (tanδ)	≤ 0.1% (0.06%*) at 1 kHz, +25°C ±5°C (* typical value)					
Test Voltage Between Terminals	The 100% screening factory test is carried out at 2,200 VDC/1,500 VAC. The voltage level is selected to meet the requirements in applicable equipment standards. All electrical characteristics are checked after the test. It is not permitted to repeat this test as there is a risk to damage the capacitor. KEMET is not liable in such case for any failures.					
	Measured at +25°C ±5°C, according to IEC 60384−2					
	Minimum Values Between Terminals					
Insulation Resistance	Voltage Charge	Voltage Charge Time	C ≤ 0.33 µF	C > 0.33 µF		
	100 VDC	1 minute	$\geq 1 \cdot 10^5 \mathrm{M}\Omega$ ($\geq 5 \cdot 10^5 \mathrm{M}\Omega$)*	≥ 30,000 MΩ • μF (≥ 150,000 MΩ • μF)*		
In DC Applications	Recommended voltage :	≤ 560 VDC				

^{*} Typical value

Impedance Graph





Environmental Test Data

Test	IEC Publication	Procedure
Endurance	EN/IEC 60384-14	$1.25 \text{x} \text{V}_{\text{R}} \text{VAC} 50 \text{Hz}$, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10 – 55 Hz at 0.75 mm or 98 m/s²
Bump	IEC 60068-2-29 Test Eb	1,000 bumps at 390 m/s ²
Change of Temperature	IEC 60068-2-14 Test Na	Upper and lower rated temperature 5 cycles
Active Flammability	IEC 60384-14	V _R + 20 surge pulses at 2.5 kV (pulse every 5 seconds)
Passive Flammability	IEC 60384-14	IEC 60384-1, IEC 60695-11-5 Needle flame test
Damp Heat Steady State	IEC 60068-2-78 Test Cab	+40°C and 93% RH, 56 days

Approvals

Mark	Specification	File Number
	EN/IEC 60384-14	CA08.00063
c 511°us	UL 60384-14 and CAN/CSA E60384-14 (310VAC)	E97797
Cec	IEC 60384-14	CQC15001128630 CQC15001128703 CQC15001128705

Environmental Compliance

All KEMET EMI capacitors are RoHS Compliant.



Table 1 – Ratings & Part Number Reference

Capacitance	Dime	ensions ir	n mm	Lead Spacing	dV/dt	New KEMET	Legacy Part
Value (µF)	В	Н	L	(p)	(V/µs)	Part Number	Number
0.010	5.0	11.0	13.0	10.0	500	46KF2100(1)H1(2)	R46KF2100(1)H1(2)
0.015	5.0	11.0	13.0	10.0	500	46KF2150(1)H1(2)	R46KF2150(1)H1(2)
0.022	5.0	11.0	13.0	10.0	500	46KF2220(1)H1(2)	R46KF2220(1)H1(2)
0.033	5.0	11.0	13.0	10.0	500	46KF2330(1)H1(2)	R46KF2330(1)H1(2)
0.047	6.0	12.0	13.0	10.0	500	46KF2470(1)H1(2)	R46KF2470(1)H1(2)
0.068	6.0	12.0	13.0	10.0	500	46KF2680(1)H1(3)	R46KF2680(1)H1(3)
0.010	5.0	11.0	18.0	15.0	400	46KI2100(1)H1(2)	R46KI2100(1)H1(2)
0.015	5.0	11.0	18.0	15.0	400	46KI2150(1)H1(2)	R46KI2150(1)H1(2)
0.022	5.0	11.0	18.0	15.0	400	46KI2220(1)H1(2)	R46KI2220(1)H1(2)
0.033	5.0	11.0	18.0	15.0	400	46KI2330(1)H1(2)	R46KI2330(1)H1(2)
0.047	5.0	11.0	18.0	15.0	400	46KI2470(1)H1(2)	R46KI2470(1)H1(2)
0.068	5.0	11.0	18.0	15.0	400	46KI2680(1)H1(2)	R46KI2680(1)H1(2)
0.10	6.0	12.0	18.0	15.0	400	46KI3100(1)H1(2)	R46KI3100(1)H1(2)
0.15	6.0	17.5	18.0	15.0	400	46KI3150(1)H2(2)	R46KI3150(1)H2(2)
0.15	9.0	12.5	18.0	15.0	400	46KI3150(1)H3(2)	R46KI3150(1)H3(2)
0.15	7.5	13.5	18.0	15.0	400	46KI3150(1)H1(2)	R46KI3150(1)H1(2)
0.22	8.5	14.5	18.0	15.0	400	46KI3220(1)H1(2)	R46KI3220(1)H1(2)
0.22	6.0	17.5	18.0	15.0	400	46KI3220(1)H2(3)	R46KI3220(1)H2(3)
0.22	9.0	12.5	18.0	15.0	400	46KI3220(1)H3(3)	R46KI3220(1)H3(3)
0.22	7.5	18.5	18.0	15.0	400	46KI3220(1)H4(2)	R46KI3220(1)H4(2)
0.33	10.0	16.0	18.0	15.0	400	46KI3330(1)H1(3)	R46KI3330(1)H1(3)
0.33	7.5	18.5	18.0	15.0	400	46KI3330(1)H2(3)	R46KI3330(1)H2(3)
0.33	13.0	12.0	18.0	15.0	400	46KI3330(1)H3(3)	R46KI3330(1)H3(3)
0.47	11.0	19.0	18.0	15.0	400	46KI3470(1)H1(3)	R46KI3470(1)H1(3)
0.15	6.0	15.0	26.5	22.5	200	46KN3150(1)H1(2)	R46KN3150(1)H1(2)
0.22	6.0	15.0	26.5	22.5	200	46KN3220(1)H1(2)	R46KN3220(1)H1(2)
0.33	7.0	16.0	26.5	22.5	200	46KN3330(1)H1(2)	R46KN3330(1)H1(2)
0.47	10.0	18.5	26.5	22.5	200	46KN3470(1)H1(2)	R46KN3470(1)H1(2)
0.68	11.0	20.0	26.5	22.5	200	46KN3680(1)H1(2)	R46KN3680(1)H1(2)
1.0	13.0	22.0	26.5	22.5	200	46KN4100(1)H1(2)	R46KN4100(1)H1(2)
Capacitance Value (μF)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	dV/dt (V/μs)	New KEMET Part Number	Legacy Part Number

⁽¹⁾ Insert lead and packaging code. See Ordering Options Table for available options.

⁽²⁾ $M = \pm 20\%$, $K = \pm 10\%$

⁽³⁾ $M = \pm 20\%$ (only available tolerance).



Soldering Process

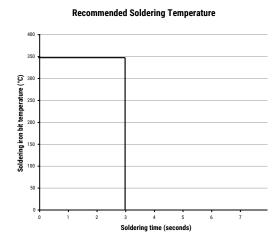
The implementation of the RoHS directive has resulted in the selection of SnAgCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from that of 183°C for SnPb eutectic alloy to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher preheat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 mm to 15 mm), and great care has to be taken during soldering. The recommended solder profiles from KEMET should be used. Please consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760–1 Edition 2 serves as a solid guideline for successful soldering. Please see Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above the recommended limits may result to degradation or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after the curing of surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Please allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

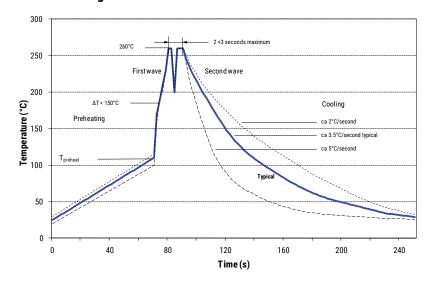
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum) with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont'd

Wave Soldering Recommendations cont'd

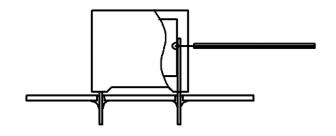
1. The table indicates the maximum set-up temperature of the soldering process Figure 1

Dielectric		imum Pre emperatu		Maximum Peak Soldering Temperature		
Film Material	Capacitor Pitch ≤ 10 mm	Pitch Pitch Pitc		Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	130°C	270°C	270°C	
Polypropylene	100°C	110°C	130°C	260°C	270°C	
Paper	130°C	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor:

Set the temperature so that inside the element the maximum temperature is below the limit:

Dielectric Film Material	Maximum temperature measured inside the element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

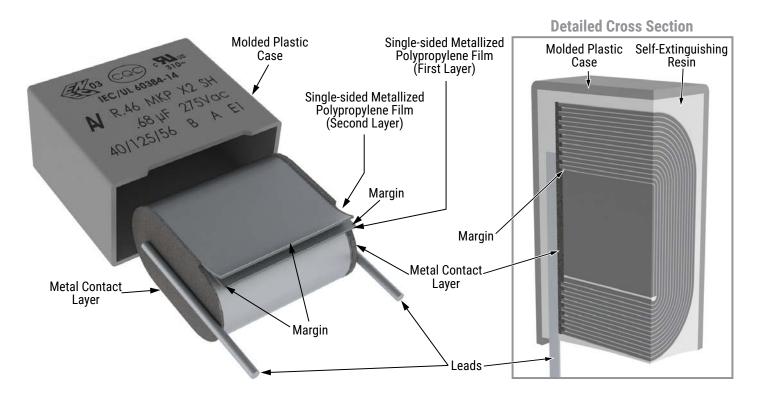
Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as in normal flow soldering without touching the solder. When the board is over the bath, it is stopped and pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

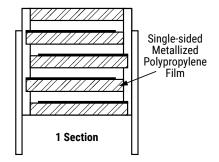
The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document, however, instead of two baths, there is only one bath with a time from 3 to 10 seconds. In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts are not overheated.



Construction



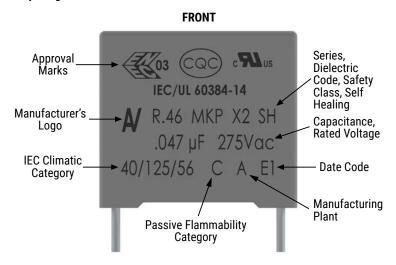
Winding Scheme

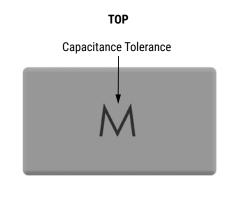




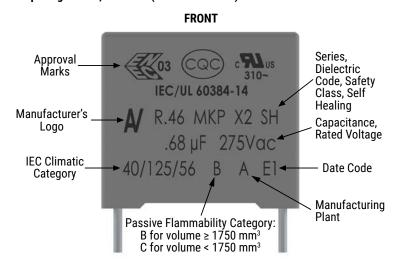
Marking

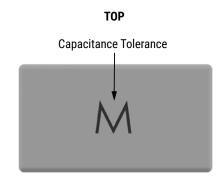
Lead Spacing 10 mm





Lead Spacing 15 mm, 22.5 mm (small case sizes)





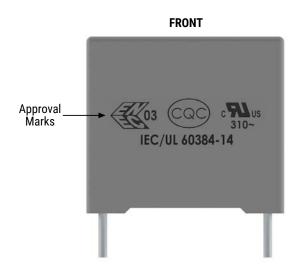


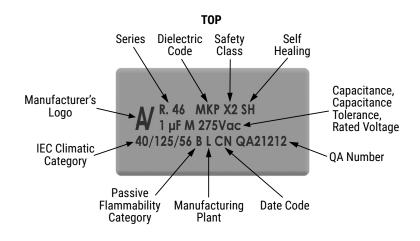
R. 46 MKP X2 SH
1 µF M 275Vac
40/125/56 B L CN QA21212

11



Marking cont'd





Mar	Manufacturing Date Code (IEC 60062)							
	Y = Year, Z = Month							
Year	Code	Month	Code					
2000	М	January	1					
2001	N	February	2					
2002	Р	March	3					
2003	R	April	4					
2004	S	May	5					
2005	Т	June	6					
2006	U	July	7					
2007	V	August	8					
2008	W	September	9					
2009	Х	October	0					
2010	Α	November	N					
2011	В	December	D					
2012	С							
2013	D							
2014	E							
2015	F							
2016	Н							
2017	J							
2018	K							
2019	L							
2020	М							



Packaging Quantities

Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel ø 355 mm	Large Reel ø 500 mm	Ammo Taped
10	5	11	13	1,300	1,500	600	1,250	800
10	6	12	13	1,000	1,200	500	1,000	680
	_		10		1.000		1.0=0	
	5	11	18	2,000	1,000	600	1,250	800
	6	12	18	1,750	900	500	1,000	680
	6	17.5	18	1,000	700	500	1,000	680
	7.5	13.5	18	1,000	700	350	800	500
15	7.5	18.5	18	900	500	-	800	500
15	8.5	14.5	18	1,000	500	300	700	440
	9	12.5	18	1,000	520	270	650	410
	10	16	18	750	500	300	600	380
	11	19	18	450	350	-	500	340
	13	12	18	750	490	200	480	280
		15	26.5	005	F00		700	46.4
	6	15	26.5	805	500	-	700	464
	7	16	26.5	700	500	-	550	380
22.5	10	18.5	26.5	396	300	-	350	235
	11	20	26.5	360	250	-	350	217
	13	22	26.5	300	200	ı	300	ı

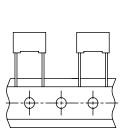


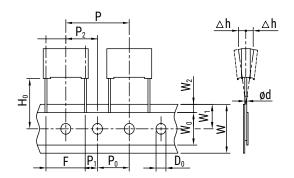
Lead Taping & Packaging (IEC 60286-2)

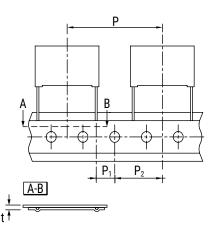
Figure 1 **Lead Spacing 10 mm**

Figure 2 Lead Spacing 15 mm

Figure 3 Lead Spacing 22.5 - 27.5 mm







Taping Specification

Description	Symbol	Dimensions (mm)				
		Lead Space				
		10	15	22.5	27.5	Tol.
		Fig. 1	Fig. 2	Fig. 3	Fig. 3	
Lead wire diameter	d	0.6	0.6-0.8	0.8	0.8	±0.05
Taping lead space	Р	25.4	25.4	38.1	38.1	±1
Feed hole lead space *	P_0	12.7	12.7	12.7	12.7	±0.2 **
Centering of the lead wire	P ₁	7.7	5.2	7.8	5.3	±0.7
Centering of the body	P ₂	12.7	12.7	19.05	19.05	±1.3
Lead spacing (pitch) ***	F	10	15	22.5	27.5	+0.6/-0.1
Component alignment	Δh	0	0	0	0	±2
Height of component from tape center	H ₀ ****	18.5	18.5	18.5	18.5	±0.5
Carrier tape width	W	18	18	18	18	+1 / -0.5
Hold down tape width	W_{0}	9	10	10	10	Minimum
Hole position	W ₁	9	9	9	9	±0.5
Hold down tape position	W ₂	3	3	3	3	Maximum
Feed hole diameter	D ₀	4	4	4	4	±0.2
Total tape thickness	t	0.7	0.7	0.7	0.7	±0.2

^{*} Available also in 15 mm.

^{**} Maximum 1 mm on 20 lead spaces.

^{***} Pitches 15 mm and 10 mm taped to 7.5 mm (crimped leads) available upon request.

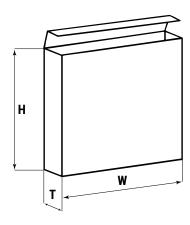
^{****} H_0 = 16.5 mm available upon request.



Lead Taping & Packaging (IEC 60286-2) cont'd

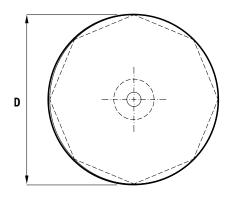
Ammo Specifications

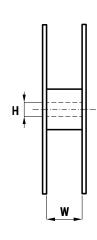
Dimensions (mm)						
Н	W	T				
360	340	59				



Reel Specifications

Reel Size	Dimensions (mm)				
Reel Size	D	Н	W		
Standard	355	30	55 Maximum		
Large	500	25			







KEMET Electronics Corporation Sales Offices

For a complete list of our global sales offices, please visit www.kemet.com/sales.

Disclaimer

All product specifications, statements, information and data (collectively, the "Information") in this datasheet are subject to change. The customer is responsible for checking and verifying the extent to which the Information contained in this publication is applicable to an order at the time the order is placed.

All Information given herein is believed to be accurate and reliable, but it is presented without guarantee, warranty, or responsibility of any kind, expressed or implied.

Statements of suitability for certain applications are based on KEMET Electronics Corporation's ("KEMET") knowledge of typical operating conditions for such applications, but are not intended to constitute – and KEMET specifically disclaims – any warranty concerning suitability for a specific customer application or use. The Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by KEMET with reference to the use of KEMET's products is given gratis, and KEMET assumes no obligation or liability for the advice given or results obtained.

Although KEMET designs and manufactures its products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product-related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicted or that other measures may not be required.